| | <specif< td=""><td>ICATION²</td><td>></td></specif<> | ICATION ² | > | | | |
|----------------------|--|----------------------|--------------------------|--|--|--|
| То : | | SPE Date | EC.No. ASDIQ-SPE-015(02) | | | |
| | | | | | | |
| | | | | | | |
| | CUSTOMER'S PRC | | I | | | |
| | COSTOMENOTING | | | | | |
| | ASDI PRODUCT NAME: | | | | | |
| | SIPM0410A-SERII | ES | | | | |
| | | | | | | |
| | | | | | | |
| RECEIPT CONFIRMATION | CONSENT | | TIONAL CONSENT | | | |
| APP | ROVED | CHE | CKED | | | |
| | | | | | | |
| ASDI SIGNATURE | | | | | | |
| ASDI SIGNATORE | CHECKED | PREPARED | | | | |
| Xianglong Li | Liang Wang | Jiayin Cai | | | | |



Xiamen ASDI Electronics Co.,Ltd.

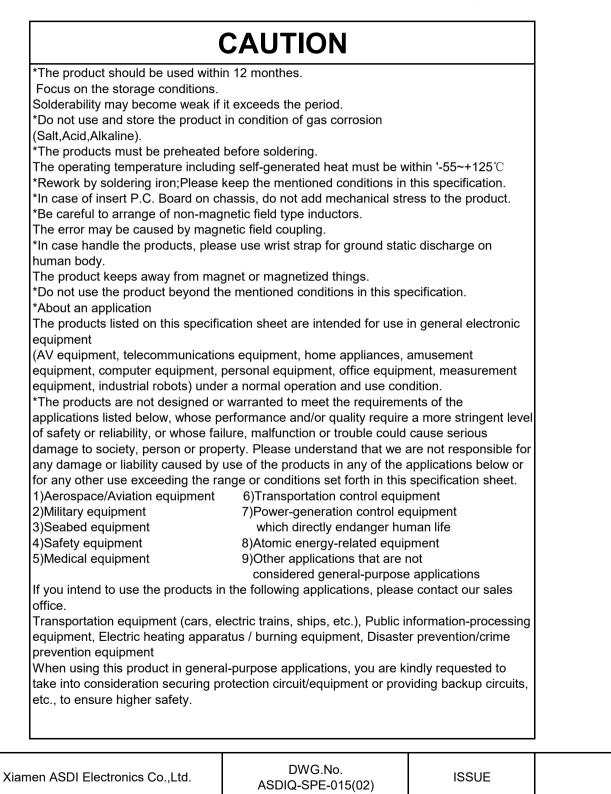
| REV. | DATE | DESCRIPTION | APPROVED | CHECKED | PREPARED |
|------|--------------|-------------|--------------|------------|------------|
| 00 | May. 24,2019 | New release | Xianglong Li | Liang Wang | Jiayin Cai |
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CAUTION WHEN HANDLING

Before use the products, please read this specification.

CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.



| CUSTOMER | ASDI PART No. | CUSTOMER'S DWG NO. |
|------------------|------------------|--------------------|
| Each Corporation | SIPM0410A-SERIES | |

1.Applications

Note PC power system, incl. IMVP-6, Switch and servers,Base stations Battery powered devices,SSD modules,DC/DC converter .

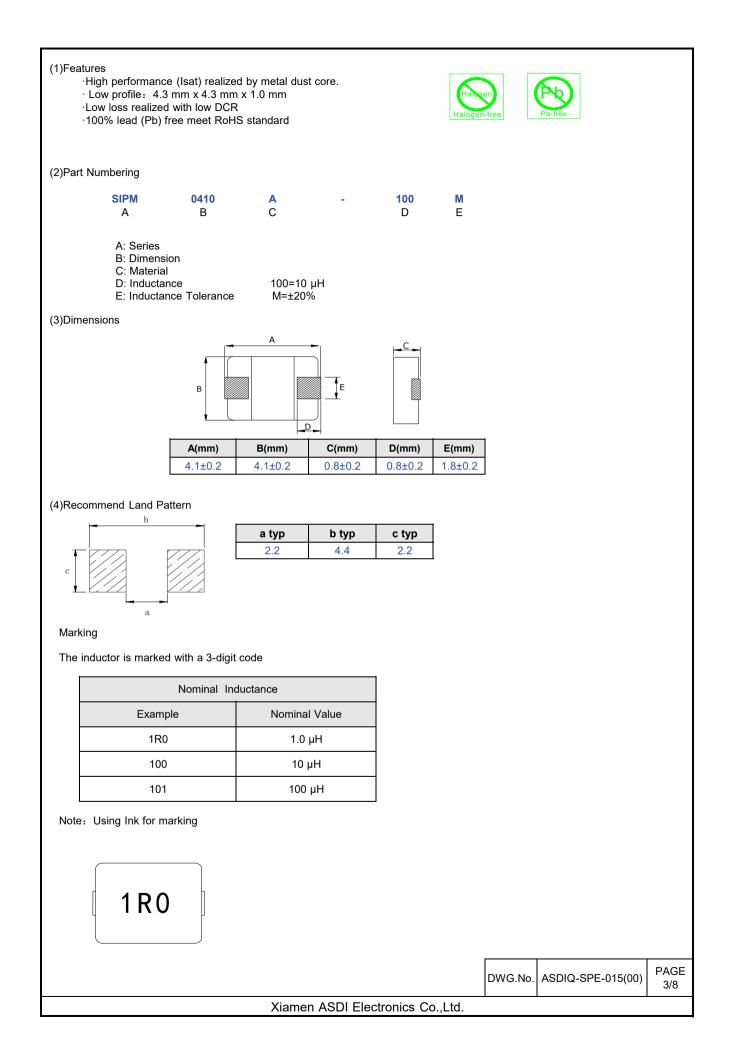
2.INDEX

| Listed item | Attachment&Tables | Page |
|-----------------------------|-------------------|------|
| 1.Features | Please see (1) | 3/8 |
| 2.Part Numbering | Please see (2) | 3/8 |
| 3.Dimensions | Please see (3) | 3/8 |
| 4.Recommend Land Pattern | Please see (4) | 3/8 |
| 5.Electrical Specifications | Please see (5) | 4/8 |
| 6.Structure and Components | Please see (6) | 5/8 |
| 7.Reliability Tests | Please see (7) | 5/8 |
| 8.Soldering and Mounting | Please see (8) | 6/8 |
| 9.Packaging Information | Please see (9) | 6/8 |
| 10.Note | Please see (10) | 8/8 |

3.Manufacturing Location

China

| | DWG.No. | ASDIQ-SPE-015(00) | PAGE 2/8 |
|-----------------------|-------------|-------------------|-------------|
| Xiamen ASDI Electroni | cs Co.,Ltd. | | |



(5)Electrical Specifications Table 1

| | Inductance | DC Resistance | Saturation Current | | Heating Rating Current | |
|------------------|--------------------|------------------|--------------------|----------|---------------------------|-----|
| ASDI Part Number | L0(µH) | DCR (mΩ) | | | Irms (A) | |
| | ±20% 100 kHz/1V | MAX | TYP. | TYP. MAX | | MAX |
| SIPM0410A-2R2M | 2.20 | 100 | 4.3 | 3.50 | 3.4 | 3.0 |
| SIPM0410A-3R3M | 3.30 | 130 | 2.8 | 2.40 | 2.3 | 2.0 |
| SIPM0410A-4R7M | 4.70 | 160 | 2.5 | 2.10 | 2.6 | 2.3 |
| SIPM0410A-6R8M | 6.80 | 255 | 2.2 | 1.85 | 2.0 | 1.8 |
| SIPM0410A-100M | 10.00 | 336 | 1.8 | 1.60 | 1.5 | 1.3 |

Note:

1. All test data is referenced to 25 °C ambient

2. Operating temperature range - 55 °C to + 125 °C

3. Irms (A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25 °C)

4. Isat(A):DC current (A) that will cause L0 to drop approximately 30 %

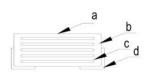
5. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions.

Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

| DWG.N | о. | ASDIQ-SPE-015(00) | PAGE 4/8 |
|----------------------------------|----|-------------------|-------------|
| Xiamen ASDI Electronics Co.,Ltd. | | | |
| | | | |

(6)Structure and Components

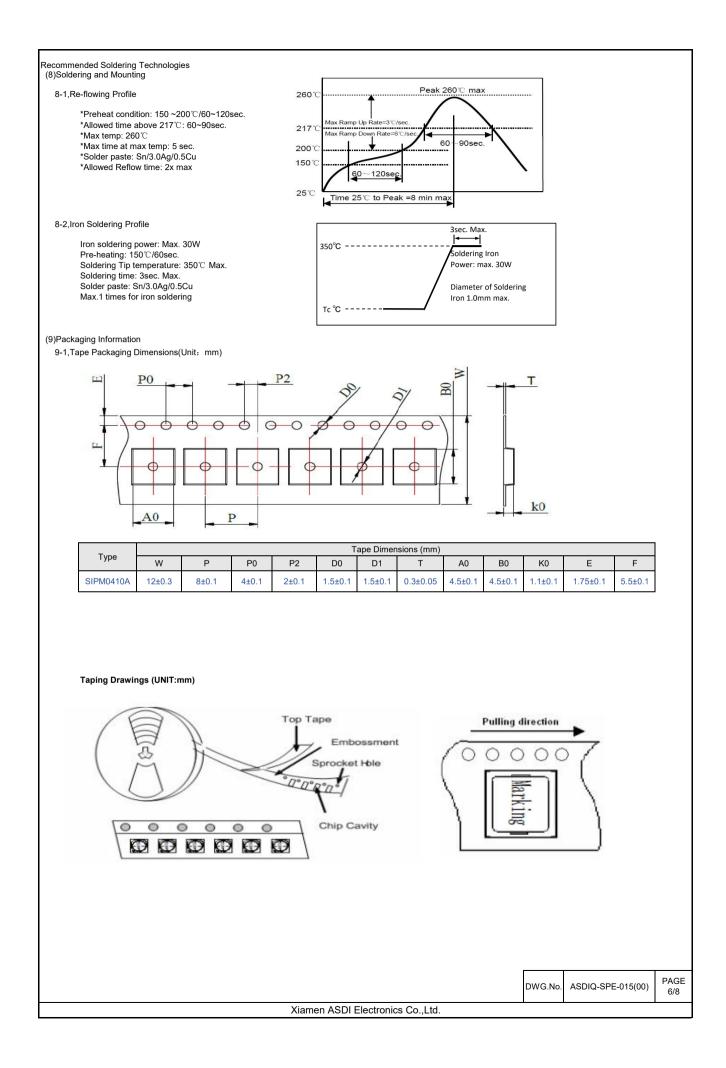
| Symbol | Components | Material | |
|--------|------------|----------------------------|--|
| а | Marking | Ink (black) | |
| b | Core | Alloy Spongy Powder | |
| с | Wire | Polyamideimide copper wire | |
| d | Terminal | Copper plated with Sn | |

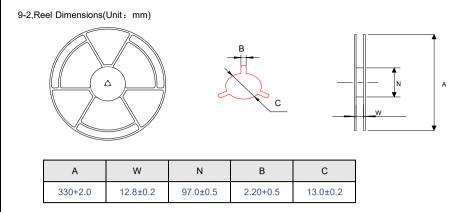


(7)Reliability Tests

| | _ | Mechanical Reliability | |
|-----|-----------------------------|---|---|
| No. | Test item | Performance | Test details |
| 1 | Solderability | 1. No case deformation or change in apperarance 2. New solder coverage more than 95% | 1.Preheat: 155℃±5℃, 60S±2S 2.Solder: lead-free. 3.Temperature: 240℃±5℃, flux 3.0S±0.5S. |
| 2 | Mechanical shock | 1. No case deformation or change in apperarance 2. △L/Lo≦±10% | 1. Acceleration: 100G 2. Pulse time:: 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions |
| 3 | Mechanical vibration | 1.No case deformation or change in apperarance 2. △L/Lo≦±10% | 1. Reflow: 2times 2. Frequency: 10HZ~55HZ~10HZ, 20 Min/Cycles 3. Amplitude: 1.52 mm 4. Directions: X,Y,Z 5. Time: 12 cycle / direction |
| | | Endurance and Reliability Test | |
| No. | Test item | Performance | Test details |
| 4 | Thermal shock test | Inductance change: Within ± 10% Without distinct damage in appearance | First -55°C for 30 minutes, last 12 °C for 30 minutes as 1 cycle. Go through 1000 cycles. Max transfer time is 3 minutes. Measured at room temperature after placing for 24±2 hours |
| 5 | Humidity Resistance | Inductance change: Within ± 10% Without distinct damage in appearance | 1.Reflow 2 times, 2.85°C,85%RH,1000 hours 3.Measured at room temperature afte placing for 24±2 hours |
| 6 | Low temperature storage | Inductance change: Within ± 10% Without distinct damage in appearance | Temperature: -55 ± 2°C Time: 1000 hours Measured at room temperature after placing for 24±2 hours |
| 7 | High temperature storage | Inductance change: Within ± 10% Without distinct damage in appearance | 1. Temperature: +125 ± 2°C 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours |

| | | <u>г</u> | |
|------------|----------------------|-------------------|-------------|
| | DWG.No. | ASDIQ-SPE-015(00) | PAGE 5/8 |
| Xiamen ASD | Electronics Co.,Ltd. | | |
| | | | |





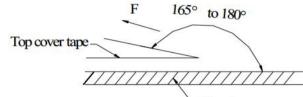
9-3, Packaging Quantity (PCS)

| Turne | Standard Quantity | | | |
|-----------|-------------------|-------------------------|---------------------------------|--|
| Туре | Reel | Inner box | Carton box | |
| SIPM0410A | 5000 pcs / reel | 2Reel / box (10000 pcs) | 4 Middle boxes, (40,000 pcs) | |

9-4, Peel force of top cover tape

The peel speed shall be about 300mm/minute

The peel force of top cover tape shall be between 0.1 to 1.3 N



Base tape

9-5,Reel Label

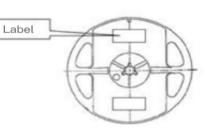
- ·Label on the reel ·Customer's part Number
- ·Lot Number
- ·Quantity
- ·Date code

·Shipping Label

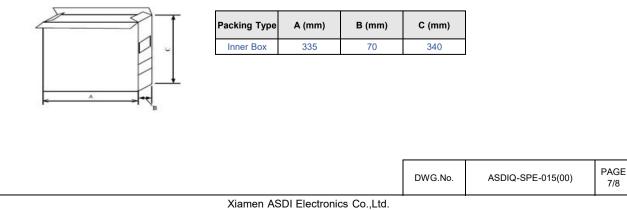
- ·Customer's part Number
- ·Manufacturer's part Number

·Quantity

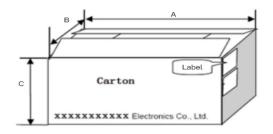
·Date code



9-6,Inner Box



9-7,Carton



| Packing Type | A (mm) | B (mm) | C (mm) |
|--------------|--------|--------|--------|
| Туре | 360 | 360 | 360 |

(10)Note

·Storage Conditions

- To maintain the solderability of terminal electrodes:
- 1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- Temperature and humidity conditions: Temperature: 5 to 30deg.C, Humidity: 75% Max.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air. Transportation
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.